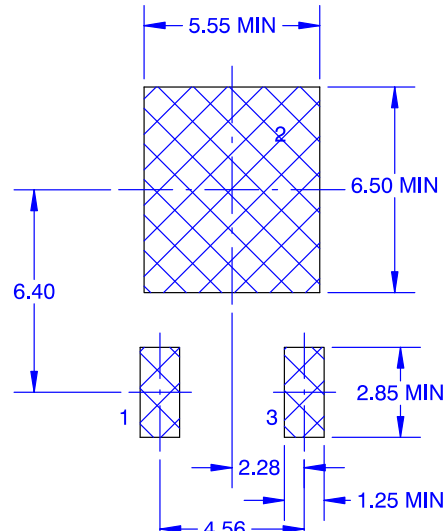
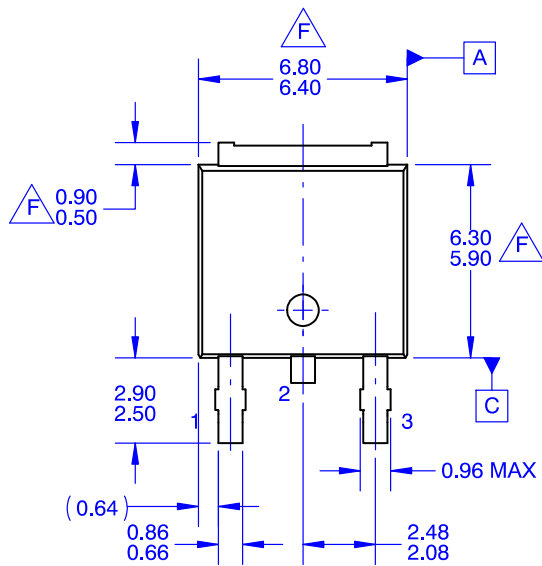
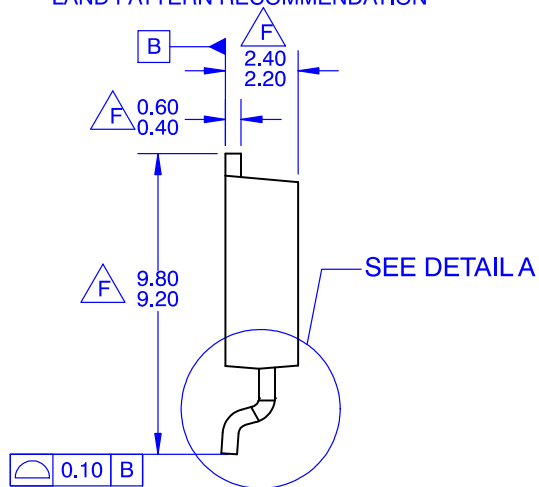
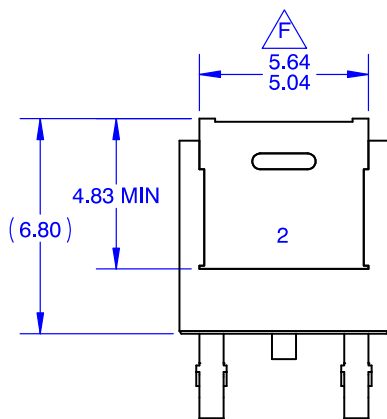


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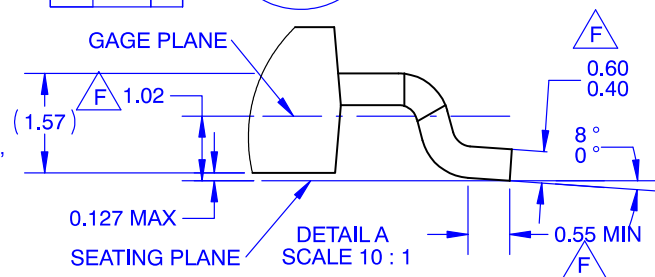


LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- A) NOT COMPLIANT TO JEDEC TO-252 VARIATION AB
- B) ALL DIMENSION ARE IN MILLIMETER
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D) LAND PATTERN PER IPC7351A STANDARD TO228P991X239-3N
- E) DOES NOT COMPLY TO JEDEC STANDARD VALUE.



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